

C¹
--The support base 12 depicted in Figure 1 can be formed of ceramic, silicon, polycrystalline silicon or other suitable material. The support base 12 can be any shape or any size, and the actual configuration of the support base 12 will depend upon the application.--

Please replace the paragraph beginning at page 9, line 8, with the following rewritten paragraph:

C²
--Turning to Figure 2, one portion, section A, of the MCM module 10 depicted in Figure 1 is shown in greater detail. Specifically, Figure 2 presents an enlarged view of section A of the MCM module 10, and more specifically depicts the decoupling capacitor 14 which is embedded within the interconnect layer 16. Figure 2 presents a cross-sectional view of this portion of the MCM device 10 which cross-sectional view illustrates that the MCM device 10 is a multilayer device. Figure 2 further shows that the decoupling capacitors 14 can be electrically coupled to the ground plane 33 and power plane 31 of the MCM module 10. Figure 2 further depicts that the interconnect layer 16 can include a plurality of layers that can be organized into a pattern of circuit connections that can be employed for interconnecting the circuit devices 20 mounted to the surface 18 of the interconnect layer 16. Figure 2 further shows that the interconnect layer 16 can include power and ground connections, 31 and 33, that can provide power to the circuit devices 20 and which are decoupled by the decoupling capacitors 14. In certain exemplary embodiments, the decoupling capacitor 14 may be connected in parallel with the power plane 31 and the ground plane 33.--

Please replace the paragraph beginning at page 9, line 23, with the following rewritten paragraph:

C³
--Specifically, Figure 2 illustrates that the capacitors 14 can have pads 26 located on an upper surface of the capacitors 14. The pads 26 can provide contact points that are electrically connected to the power plane 28 and ground plane 29 that form capacitor 14. The interconnect layer 16 includes metal layers, such as the ground layer 33 and the power layer 31, that connect to these contact points and therefore extend the ground plane 29 and power plane 28 of the capacitor 14. The metal layers can connect, optionally in almost a direct line, through the interconnect layer 16 and to the power and ground connections of the circuit devices 20. In this